

## PMP8629 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C18	2	1uF	STD	STD	Capacitor, Ceramic,	0805
C2, C3, C4, C5, C6, C8, C9, C10, C11, C12, C19, C20, C21, C22, C23, C24, C25, C26, C27, C28	20	10uF	GRM32ER71H106KA12	Murata	Capacitor, Ceramic, 50V, X7R, 10%	1210
C7	1	1nF	Std	Std	Capacitor, Ceramic, 50V, X7R,10%	0402
C13, R6, R9	3	DNP	Std	Std	Capacitor, Ceramic, 50V, X7R,10%, Resistor, Chip, 1/16-W, 1%, Resistor, Chip, 1/16-W, 1%	0402
C14	1	100nF	Std	Std	Capacitor, Ceramic, 25V, X7R, 10%	0603
C15	1	12pF	STD	Std	Capacitor, Ceramic, 50V, NPO, 10%	0402
C16	1	1.2nF	Std	Std	Capacitor, Ceramic, 50V, X7R,10%	0402
C17	1	1uF	Std	TDK	Capacitor, Ceramic, 100V, X7R, 15%	1206
C29	1	330nF	Std	Std	Capacitor, Ceramic, 50V, X7R, 10%	0603
C30	1	330pF	STD	STD	Capacitor, Ceramic,	0805
C31	1	1uF	Std	Std	Capacitor, Ceramic, 16V, X7R, 10%	0603
C32	1	1nF	Std	Std	Capacitor, Ceramic, 50V, X7R,10%	0603
C33	1	4.7uF	Std	TDK	Capacitor, Ceramic, 16V, X7R, 15%	0805
C34	1	390pF	Std	Std	Capacitor, Ceramic, 50V, X7R,10%	0402
D2	1	B380B	B380B	Diodes Incorporated	Diode, Schottky, 3-A, 80-V	SMB
J1	1	PEC03SAA N	PEC03SAAN	Sullins	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3
J2	1	ED555/2DS	ED555/2DS	OST	Terminal Block, 2-pin, 6-A, 3.5mm	0.27"x0.25"
J3	1	ED120/2DS	ED120/2DS	OST	Terminal Block, 2-pin, 15-A, 5.1mm	0.40"x0.35"
L3	1	WE 2013 series	7443631000	WE	Inductor, SMT, 10uH	0.790 x 0.770 inch
Q1	1	CSD18537 NQ5A	CSD18537NQ5A	TI nexFET	MOSFET, Nch, 60V, 11 milliohm	TDSON-8
Q2	1	CSD18563 Q5A	CSD18563Q5A	TI nexFET	MOSFET, Nch, 60V, 5.2 milliohm	TDSON-8
R1	1	301k	Std	Std	Resistor, Chip, 1/16W, 1%	0805
R2	1	1M	Std	Std	Resistor, Chip, 1/16W, 1%	0805
R3	1	1	Std	Std	Resistor, Chip, 1/16W, 1%	0805
R4, R15	2	23.2K	Std	Std	Resistor, Chip, 1/16-W, 1%	0402
R5	1	30.1K	Std	Std	Resistor, Chip, 1/16-W, 1%	0402
R7, R8, R16	3	0	Std	Std	Resistor, Chip, 1/16-W, 1%	0603
R10	1	10K	Std	Std	Resistor, Chip, 1/16-W, 1%	0402
R11	1	31.6K	Std	Std	Resistor, Chip, 1/16-W, 1%	0402
R12	1	OPEN	Std	Std	Resistor, Chip, 1/16-W, 1%	0603
R13	1	2.2	STD	STD	Resistor, Chip, 1/2W, 0.1%	1210
R14	1	10K	Std	Std	Resistor, Chip, 1/16-W, 1%	0603
R17	1	7.32K	Std	Std	Resistor, Chip, 1/16-W, 1%	0603
R18	1	1.91K	Std	Std	Resistor, Chip, 1/16-W, 1%	0603
R19	1	100K	Std	Std	Resistor, Chip, 1/16-W, 1%	0402
R20	1	49.9	Std	Std	Resistor, Chip, 1%, 0603	0603
R21	1	1K	Std	Std	Resistor, Chip, 1%, 0402	0402

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
TP1, TP2, TP4, TP5, TP6, TP7, TP8, TP11, TP12, TP13	10	5000	5000	Keystone	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch
TP3, TP9, TP10	3	5001	5001	Keystone	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch
U1	1	TPS40170R GY	TPS40170RGY	TI	IC, 4.5V-60V Wide Input Sync Buck Controller	QFN-20

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